

826632-1 ✓ ACTIVE

AMPMODU | [AMPMODU Headers](#)

TE Internal #: 826632-1

PCB Mount Header, Vertical, Board-to-Board, 1 Position, 2.54 mm [.1 in] Centerline, Breakaway, AMPMODU Headers

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Connectors > PCB Connectors > PCB Headers & Receptacles



PCB Connector Assembly Type: **PCB Mount Header**

PCB Mount Orientation: **Vertical**

Connector System: **Board-to-Board**

Number of Positions: **1**

Number of Rows: **2**

Features

Product Type Features

| | |
|-----------------------------------|-----------------------|
| PCB Connector Assembly Type | PCB Mount Header |
| Connector System | Board-to-Board |
| Header Type | Breakaway |
| Sealable | No |
| Connector & Contact Terminates To | Printed Circuit Board |

Configuration Features

| | |
|----------------------------------|--------------|
| Connector Contact Load Condition | Fully Loaded |
| PCB Mount Orientation | Vertical |
| Number of Positions | 1 |
| Number of Rows | 2 |
| Board-to-Board Configuration | Parallel |

Electrical Characteristics

| | |
|---------------------------------------|----------|
| Insulation Resistance | 5000 MΩ |
| Dielectric Withstanding Voltage (Max) | 750 Vrms |

Body Features

| | |
|-----------------------|-------|
| Primary Product Color | Green |
|-----------------------|-------|

Contact Features

| | |
|------------------------------|-----------------|
| Mating Square Post Dimension | .63 mm[.025 in] |
|------------------------------|-----------------|



| | |
|--|--|
| Contact Shape & Form | Square |
| Contact Underplating Material | Nickel |
| PCB Contact Termination Area Plating Material | Tin |
| Contact Base Material | Brass |
| Contact Mating Area Plating Material | Gold or Gold Flash over Palladium Nickel |
| Contact Mating Area Plating Material Thickness | .8 μm [31.5 μin] |
| Contact Type | Pin |
| Contact Current Rating (Max) | 5 A |

Termination Features

| | |
|---|-----------------------|
| Square Termination Post & Tail Dimension | .63 mm[.025 in] |
| Termination Post & Tail Length | 3.2 mm[.126 in] |
| Termination Method to Printed Circuit Board | Through Hole - Solder |

Mechanical Attachment

| | |
|-------------------------|-------------|
| Mating Alignment | Without |
| PCB Mount Retention | Without |
| PCB Mount Alignment | Without |
| Connector Mounting Type | Board Mount |

Housing Features

| | |
|--------------------|----------------|
| Centerline (Pitch) | 2.54 mm[.1 in] |
| Housing Material | PBT |

Dimensions

| | |
|-----------------------------|------------------|
| Row-to-Row Spacing | 2.54 mm[.1 in] |
| PCB Thickness (Recommended) | 1.57 mm[.062 in] |

Usage Conditions

| | |
|-----------------------------|--|
| Housing Temperature Rating | Standard |
| Operating Temperature Range | -65 – 105 $^{\circ}\text{C}$ [-85 – 221 $^{\circ}\text{F}$] |

Operation/Application

| | |
|------------------------|----------------|
| Solder Process Feature | Board Standoff |
| Circuit Application | Signal |

Industry Standards

| | |
|------------------------|----------|
| UL Flammability Rating | UL 94V-0 |
|------------------------|----------|

Packaging Features



| | |
|--------------------|------|
| Packaging Quantity | 3000 |
| Packaging Type | Box |

Product Compliance

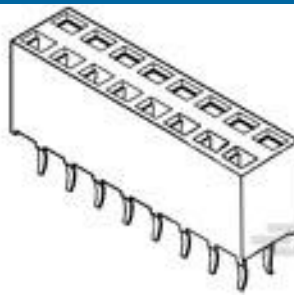
[For compliance documentation, visit the product page on TE.com>](#)

| | |
|---|--|
| EU RoHS Directive 2011/65/EU | Compliant |
| EU ELV Directive 2000/53/EC | Compliant |
| China RoHS 2 Directive MIIT Order No 32, 2016 | No Restricted Materials Above Threshold |
| EU REACH Regulation (EC) No. 1907/2006 | Current ECHA Candidate List: JUNE 2022 (224) Candidate List Declared Against: JUL 2021 (219) Does not contain REACH SVHC |
| Halogen Content | Not Low Halogen - contains Br or Cl > 900 ppm. |
| Solder Process Capability | Wave solder capable to 265°C |

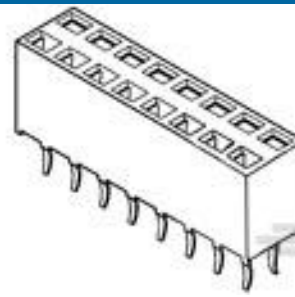
Product Compliance Disclaimer

This information is provided based on reasonable inquiry of our suppliers and represents our current actual knowledge based on the information they provided. This information is subject to change. The part numbers that TE has identified as EU RoHS compliant have a maximum concentration of 0.1% by weight in homogenous materials for lead, hexavalent chromium, mercury, PBB, PBDE, DBP, BBP, DEHP, DIBP, and 0.01% for cadmium, or qualify for an exemption to these limits as defined in the Annexes of Directive 2011/65/EU (RoHS2). Finished electrical and electronic equipment products will be CE marked as required by Directive 2011/65/EU. Components may not be CE marked. Additionally, the part numbers that TE has identified as EU ELV compliant have a maximum concentration of 0.1% by weight in homogenous materials for lead, hexavalent chromium, and mercury, and 0.01% for cadmium, or qualify for an exemption to these limits as defined in the Annexes of Directive 2000/53/EC (ELV). Regarding the REACH Regulation, the information TE provides on SVHC in articles for this part number is based on the latest European Chemicals Agency (ECHA) 'Guidance on requirements for substances in articles' posted at this URL: <https://echa.europa.eu/guidance-documents/guidance-on-reach>

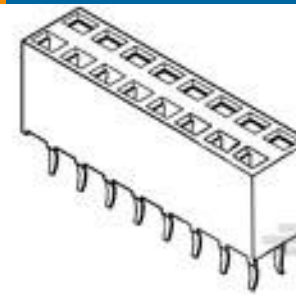
Compatible Parts



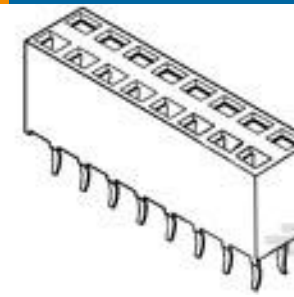
TE Part # 2-215307-9
2X29P HV100 REC CON. TE, 7.0MM



TE Part # 2-215307-1
2X21P HV100 REC CON. TE, 7.0MM



TE Part # 2-215309-9
2X29P HV100 REC CON. TE, 8.5MM



TE Part # 3-215309-1
2X31P HV100 REC CON. TE, 8.5MM

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Wire-to-Board Connector Assemblies
& Housings(5)

Wire-to-Board Connector Contacts(66)

Documents

Product Drawings

1P AMPMODU II PIN HDR

English

CAD Files

3D PDF

3D

Customer View Model

[ENG_CVM_CVM_826632-1_R.2d_dxf.zip](#)

English

Customer View Model

[ENG_CVM_CVM_826632-1_R.3d_igs.zip](#)

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Customer View Model

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Agency Approvals

UL Report

English